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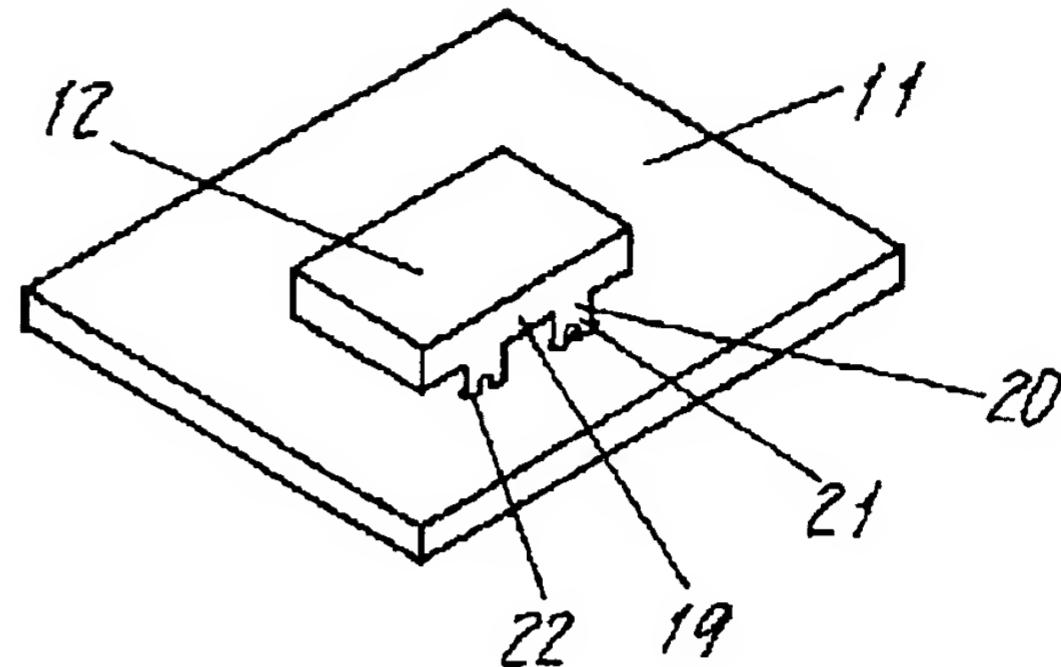
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TITLE : SOLDERING STRUCTURE OF
ELECTRONIC APPARATUS



ABSTRACT : PROBLEM TO BE SOLVED: To improve the reliability of the attachment of a high frequency unit of which an electronic apparatus is composed.

SOLUTION: An electronic apparatus has a mother printed board 11 on which electronic components are mounted, a frame 19 to which the mother printed board 11 is attached, a plurality of legs 20 provided on the lower part of the frame 19 and pairs of protrusions 21 formed on the respective tips of the legs 20. Through-holes 22 into which the protrusions 21 are inserted are formed in the mother printed board 11. With this constitution, the reliability of the attachment of a high frequency unit 12 of which the electronic apparatus is composed can be improved.

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